

**AMENDMENT TO THE CLAIMS**

*The following claim listing replaces all prior listings and versions of the claims:*

**LISTING OF CLAIMS**

1. (Withdrawn) Soldering paste to be disposed between a solder portion formed on a first electrode and a second electrode when the first electrode with the solder portion is soldered to the second electrode, comprising:

liquid basis formed of resin component;

an activator removing oxide film produced on surfaces of the solder portion; and

metal powder including a core metal and a surface metal to cover surfaces of the core metal,

wherein the surface metal has excellent wettability for solder of the solder portion formed on a first electrode, and the core metal is capable of taking the surface metal into itself by dissolving it under heat in a reflow process.

2. (Withdrawn) The soldering paste of claim 1, wherein the core metal is selected from the group of tin, zinc, lead, and indium, and the surface metal includes any one of gold and silver.

3. (Withdrawn) The soldering paste of claim 2, wherein the core metal includes tin or tin-based alloy, and the surface metal includes silver.

4. (Currently Amended) Soldering method for soldering a first electrode with solder portion to a second electrode, comprising the steps of:

coating the soldering paste, comprising liquid basis formed of resin component, an activator removing oxide film produced on surfaces of the solder portion, and metal powder

having at least flake-like shaped metal powder including a core metal and a surface metal to cover surfaces of the core metal, on at least one of the solder portion and the second electrode;

disposing the soldering paste between the solder portion and the second electrode by positioning the first electrode and the second electrode;

letting molten solder come in contact with the first electrode and the second electrode by melting the solder under heat and wetting and spreading the molten solder along surfaces of the metal powder guiding the molten solder, and also dissolving the surface metal into the core metal to take it in; and

solidifying the molten solder after letting molten solder come in contact with the first electrode and the second electrode, wherein:

the first electrode includes at least a first bump and a second bump and the second electrode includes at least a first circuit electrode and a second circuit electrode, both of which are to be connected to the first bump and the second bump by the soldering method, respectively,  
and

in the step of letting molten solder come in contact with the first electrode, the first bump is in direct contact with the first circuit electrode, while the second bump is not in contact with the second circuit electrode.

5. (Original) The soldering method of claim 4, wherein the core metal is selected from the group of tin, zinc, lead, and indium, and the surface metal includes any one of gold and silver.

6. (Original) The soldering method of claim 5, wherein the core metal includes tin or tin-based alloy, and the surface metal includes silver.

7. (Previously Presented) The soldering paste of claim 4, wherein amount of the metal powder is 1-20 vol %.